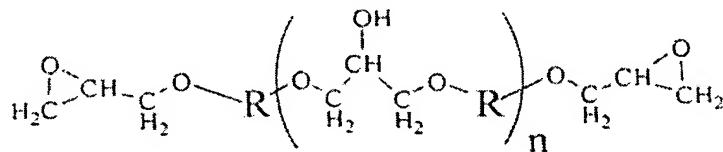


This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended): A process for production of a high-purity epoxy compound with total chlorine content of less than 500 ppm, said process comprising:  
reacting characterized in that an epoxy compound according to represented  
by the following general formula (I):

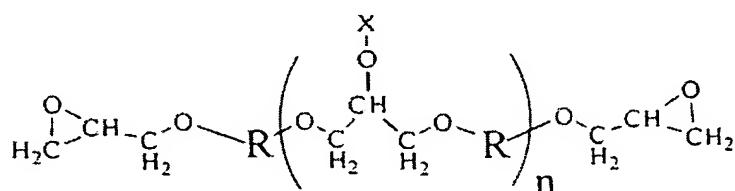


[[();]wherein,

R represents a dihydric phenol compound residue and/or a dihydric alcohol compound residue, [[;]] and

n represents a numerical value with the average greater than 0 and not greater than 10 [[]], in which the proportion of the component having n equal to 0 is more than 70% and less than 100%,

~~is caused to react in the presence of alkali metal hydroxide at temperature of 95°C - 150°C~~ 95°C - 150°C, to produce an epoxy compound according to represented by the  
following general formula (II):



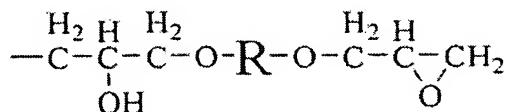
{wherein,

R represents a dihydric phenol compound residue and/or a dihydric alcohol compound

residue<sub>1</sub> [[;]]

n represents a numerical value with the average greater than 0 and not greater than 10,  
[[;]] and

X is a hydrogen atom or a group according to represented by the following general  
formula (III):



[[();]] wherein,

R has the above-described meaning ), in

which the component with X represented by the general formula (III) is always contained.

2. (Currently Amended): A process ~~for production of a high-purity epoxy~~  
~~compound~~ according to claim 1, wherein the resultant manufactured epoxy compound  
obtained by the process contains consists of the epoxy compound of represented by the  
general formula (I) in the proportion of not less than 90% and less than 100%, and the epoxy  
compound of represented by the general formula (II) in the proportion of greater than 0% and  
not greater than 10%.

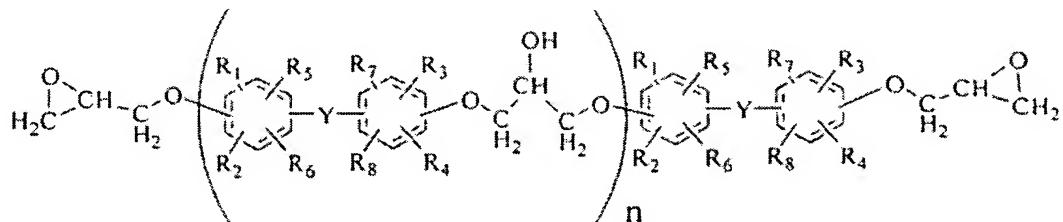
3. (Currently Amended): A process ~~for production of a high-purity epoxy~~  
~~compound~~ according to claim 1, wherein said alkali metal hydroxide is potassium hydroxide.

4. (Currently Amended): A process ~~for production of a high-purity epoxy~~  
~~compound~~ according to Claim 1, wherein 5-100 5-100 g of potassium hydroxide is used per  
1 kg of said the epoxy compound of resin represented by said general formula (I), and is used  
in the reaction in the form of aqueous solution of potassium hydroxide of 80% or higher in  
concentration.

5. (Currently Amended): A process ~~for production of a high-purity epoxy~~  
~~compound~~ according to Claim 1, wherein the reaction is conducted in the presence of a

tertiary alcohol.

6. (Currently Amended): A process for production of a high purity epoxy compound according to Claim 1, wherein said epoxy compound of ~~represented by the general formula (I) is an epoxy compound according to represented by the following general formula (IV):~~

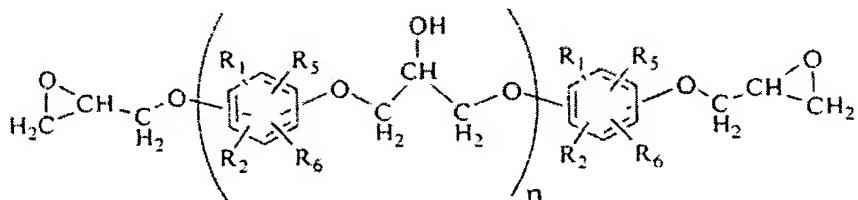


{wherein,

R<sub>1</sub>, R<sub>8</sub> R<sub>1</sub>, R<sub>8</sub> may be same or different, and each of R<sub>1</sub> - R<sub>8</sub> R<sub>1</sub> - R<sub>8</sub> is a hydrogen, alkyl, allyl, phenyl group or halogen atom, [[;]]

Y represents a direct bond, or-alkyl group with carbon number of 1 - 20 1 - 20, allyl, phenyl, aralkyl, biphenylaralkyl, oxygen, sulphur, sulfone, or carboxyl group; and

n is a numerical value with average greater than 0 and not greater than 10; } and /or an epoxy compound ~~according to represented by the following general formula (V):~~



{wherein,

R<sub>1</sub>, R<sub>2</sub>, R<sub>5</sub>, and R<sub>6</sub> represent hydrogen, alkyl, allyl, phenyl group, or halogen atom, and may be same or different; [[;]] and

n is a numerical value with average greater than 0 and not greater than 10}.

7. (Currently Amended): A process ~~for production of a high purity epoxy compound according to Claim 6 +, wherein said epoxy compound of represented by the general formula (IV) is a tetramethyl bisphenol type epoxy resin or a tetramethyl biphenyl type epoxy resin~~

8. (Currently Amended): A high purity epoxy resin composition ~~which contains, as essential components, comprising the high-purity epoxy compound obtained by the process manufacturing method according to Claim 1, and a curing agent for epoxy resins.~~

9. (Currently Amended): A method of sealing electronic components comprising sealing said electronic parts using a ~~A high purity epoxy resin composition according to claim 7 for use as sealing material for electronic parts, which contains, as essential components, the high-purity epoxy compound obtained by the manufacturing method according to Claim 1 and a curing agent for epoxy resins.~~

10. (Currently Amended): A hardened epoxy resin product ~~which is obtained by curing the epoxy resin composition according to claim 8.~~

11. (New): A process according to claim 1, wherein the resultant epoxy compound obtained by the process has a total chlorine content of less than 350 ppm.

12. (New): A process according to claim 1, wherein, for the epoxy of the compound of Formula (I) that is to be reacted, the proportion of the epoxy compound having n equal to 0 is 70% -99%.

13. (New): A process according to claim 1, wherein, for the epoxy of the compound of Formula (I) that is to be reacted, the proportion of the epoxy compound having n equal to 0 is 80% -99%.

14. (New): A process according to claim 2, wherein the resultant epoxy compound obtained by the process contains the epoxy compound of formula (II) in an

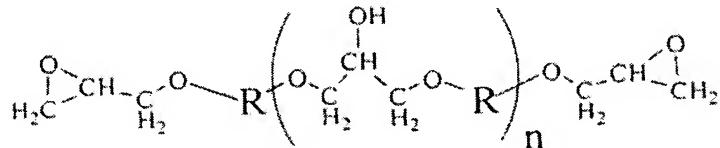
amount of 1-10%.

15. (New): A process according to claim 14, wherein the resultant epoxy compound obtained by the process contains the epoxy compound of formula (II) in an amount of 1-6%.

16. (New): A process according to claim 15, wherein the resultant epoxy compound obtained by the process contains the epoxy compound of formula (II) in an amount of 2-5%.

17. (New): A process for production of a high-purity epoxy composition with total chlorine content of less than 500 ppm, said process comprising:

reacting a first component of epoxy compounds according to formula (I)

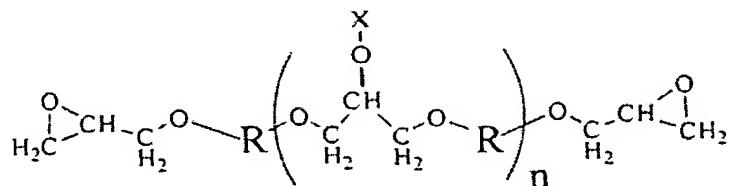


wherein,

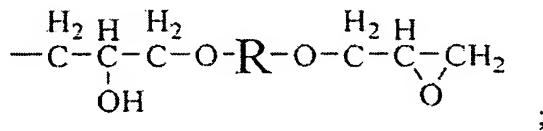
R is a dihydric phenol compound residue and/or a dihydric alcohol compound residue, and

n is a numerical value wherein the average value for n for said first component is greater than 0 and not greater than 10, and the proportion of said first component made up of compounds of formula I having n equal to 0 is more than 70% and less than 100%,

in the presence of alkali metal hydroxide at temperature of 95°C - 150°C, to produce a second component of epoxy compounds according to formula (II):



wherein X is a hydrogen atom or a group according to formula (III);

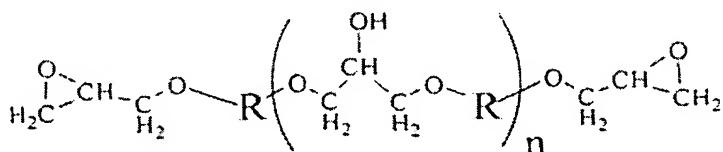


wherein the resultant epoxy composition contains epoxy compounds of formula (I) in a proportion of not less than 90% and less than 100%, and epoxy compounds of formula (II) in a proportion of greater than 0% and not greater than 10%, and

wherein said epoxy composition contains a component of epoxy compounds of formula II in which X is of formula (III).

18. (New): A high-purity epoxy compound, with total chlorine content of less than 500 ppm, obtained by a process comprising:

reacting an epoxy compound according to formula (I):

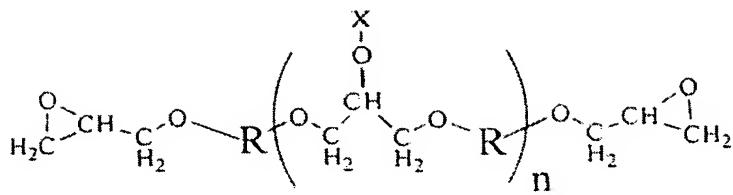


wherein,

R represents a dihydric phenol compound residue and/or a dihydric alcohol compound residue, and

$n$  represents a numerical value with the average greater than 0 and not greater than 10, in which the proportion of the component having  $n$  equal to 0 is more than 70% and less than 100%,

in the presence of alkali metal hydroxide at temperature of 95°C - 150°C, to produce an epoxy compound according to formula (II):

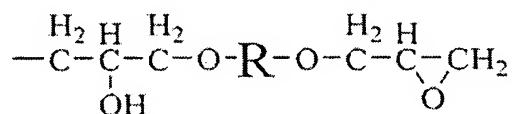


wherein,

R represents a dihydric phenol compound residue and/or a dihydric alcohol compound residue,

n represents a numerical value with the average greater than 0 and not greater than 10, and

X is a hydrogen atom or a group according to formula (III):



wherein,

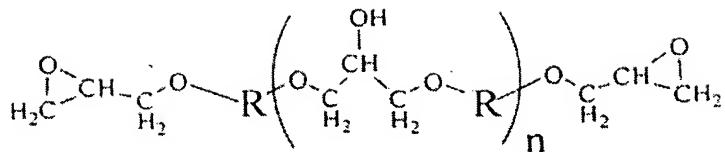
R has the above-described meaning, in

which the component with X represented by formula (III) is always contained.

19. (New): An epoxy composition comprising an epoxy compound according to claim 18, and a curing agent.

20. (New): In a method of sealing electronic components comprising sealing said electronic parts using an epoxy resin composition, the improvement wherein said epoxy resin composition contains an epoxy compound, with total chlorine content of less than 500 ppm, obtained by a process comprising:

reacting an epoxy compound according to formula (I):

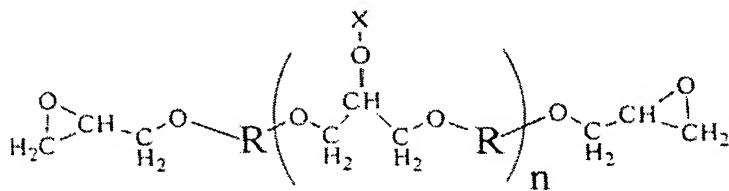


wherein,

R represents a dihydric phenol compound residue and/or a dihydric alcohol compound residue, and

n represents a numerical value with the average greater than 0 and not greater than 10, in which the proportion of the component having n equal to 0 is more than 70% and less than 100%,

in the presence of alkali metal hydroxide at temperature of 95°C - 150°C, to produce an epoxy compound according to formula (II):

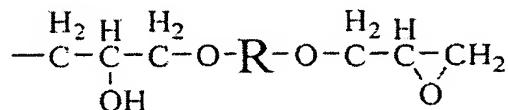


wherein,

R represents a dihydric phenol compound residue and/or a dihydric alcohol compound residue,

n represents a numerical value with the average greater than 0 and not greater than 10, and

X is a hydrogen atom or a group according to formula (III):



wherein,

R has the above-described meaning, in  
which the component with X represented by formula (III) is always contained.